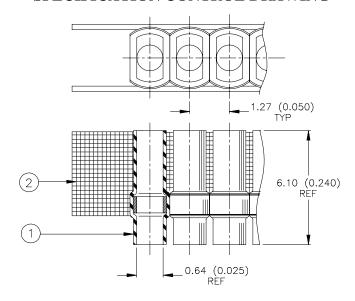
SPECIFICATION CONTROL DRAWING



MATERIALS

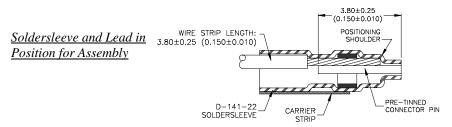
- 1. SOLDERSLEEVE: D-141-22. Quantity Per Assembly: 1000
- 2. CARRIER STRIP: Adhesive Coated High Temperature Tape

APPLICATION

- 1. This assembly is designed for use on micro-miniature connectors having a maximum pin cross sectional area envelope of 0.64 (0.025) diameter on 1.27 (0.050) center spacing.
- 2. Sleeves are to be installed using Raychem-approved convection or infrared heating tools.
- 3. The sleeves can accommodate the following wire sizes:

No. of Wires	Wire Size (AWG)
1	26
1	28
1	30
2	28 [0.81 (0.032) max. insulation O.D., 0.20 x 0.58 (0.008 x 0.023) pin]
2	30

- 4. Strip wires to 3.80 ± 0.25 (0.150 ±0.010) and position as shown.
- 5. Trim pre-tinned connector pins, as required to 3.80±0.25 (0.150±0.010).
- 6. Remove forward carrier strip after sleeves have been positioned on pins prior to termination. Rear carrier strip is to be removed upon completion of termination.



TUCO/Electronics/Raychem 307 Constitution Drive Menlo Park, CA 94025, USA				Harn	e and lessing ducts	SOLDERPAK ASSEMBLY, MICROMINIATURE CONNECTORS 1.27 (0.050) Center Spacing			
Unless otherwise specified dimensions are in millimeters. Inches dimensions are in between brackets.					DOCUMENT NO.:	D-713-02			
TOLERANCES: 0.00 N/A 0.0 N/A 0 N/A	amend this draw			es reserves the right to ving at any time. Users the suitability of the r application.		DCR NUMBER: D010415		REPLACES: N/A	
DRAWN BY: DATE: M. FORONDA 2		E: 22-Jun-01	PRO	OD. REV. B	DOC ISSUE: 1	SCALE: None	SIZE: A	SHEET: 1 of 1	